

# Driving decarbonization and digitalization. Together.



## Senior Engineer Package Technology Development

### Job description

- Deliver stable unit process development under the package development project in accordance to project timeline, yield and cost targets
- Continuous exploring on breakthrough in new unit process development and new test method or characterization development for semiconductor packaging in consideration with product, package, process or customer specific requirements
- Coordinate across internally (business divisions, segments order departments) and externally (equipment/material suppliers) to generate or update technical documentations (Chip Specification, Process Specification, Control Plan, FMEA, Failure Catalog, Procurement Specification and equipment release), requirement for equipment or material to develop stable unit process for manufacturing
- Technical lead / coach for specific Au / Cu wire bonding or Alu Wedge wire bonding process development
- Identify problem or deviation and recommend & implement corrective actions
- Derive and define new process design guideline for new package / product technologies
- Support End-to-End needs on tolling and machine ramp-up requirement
- Conduct process knowledge transfer to sustaining team

### Profile

- Work experience in years: Minimum 3 years of working experience in semiconductor industry.  
(Process Development, Process engineering, Manufacturing engineering in Assembly)
- Technical / functional experience in years: Minimum 3 years of solid experience in Wire Bonding (Au & Alu wire bonding) or FOL process  
(Equipment system & process know-how)
- Equipment hands-on, understand equipment mechanism, function & troubleshooting
- Intermediate level of written/spoken English
- Bachelor's Degree or Master's Degree in Electrical, Electronic, Mechanical, Material engineering or equivalent
- Statistical data analysis skills and problem solving skills (Minitab or JMP)
- In depth knowledge of Design of Experiment
- Auto CAD skill for tool & part design
- MS excel & PPT for strive for excellence
- Positive attitude towards work ad team activities
- Collaborate with other departments for successful new product development

### Benefits

- **Cheonan:** Wide range of training offers & planning of career development; International assignments; Different career paths: Project Management, Technical Ladder, Management & Individual Contributor; Flexible working

### At a glance

Location: **Cheonan (Korea)**  
Job ID: **HRC0745225**  
Start date: **Jun 03, 2024**  
Entry level: **5+ years**  
Type: **Full time**  
Contract: **Permanent**

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Job ID: **HRC0745225**  
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conditions; Medical Coverage; On-site canteen; Wage payment in case of sick leave; Performance bonus

## Why Us

### **Driving decarbonization and digitalization. Together.**

Infineon designs, develops, manufactures, and markets a broad range of semiconductors and semiconductor-based solutions, focusing on key markets in the automotive, industrial, and consumer sectors. Its products range from standard components to special components for digital, analog, and mixed-signal applications to customer-specific solutions together with the appropriate software.

### **We are on a journey to create the best Infineon for everyone.**

This means we embrace diversity and inclusion and welcome everyone for who they are. At Infineon, we offer a working environment characterized by trust, openness, respect and tolerance and are committed to give all applicants and employees equal opportunities. We base our recruiting decisions on the applicant 's experience and skills.

Please let your recruiter know if they need to pay special attention to something in order to enable your participation in the interview process.

[Click here](#) for more information about Diversity & Inclusion at Infineon.

